

ABSTRACT

The substrate (10) of the present invention includes:  
a first electrode (26) and a second electrode (30). The second  
5 electrode (30) is formed on an insulation film (52) covering  
at least a part of the first electrode (26) and electrically  
connected with the first electrode (26) through a contact  
hole (50) formed in the insulation film (52). The first  
electrode (26) includes a laminated structure of a metal  
10 film (42) and a protective film (44). An etching rate of  
the metal film (42) is almost equal to an etching rate of  
the protective film (44) with respect to a first etching  
for forming the metal film (42) and the protective film (44).  
An etching rate of the protective film (44) is almost zero  
15 with respect to a second etching for forming the contact  
hole (50).